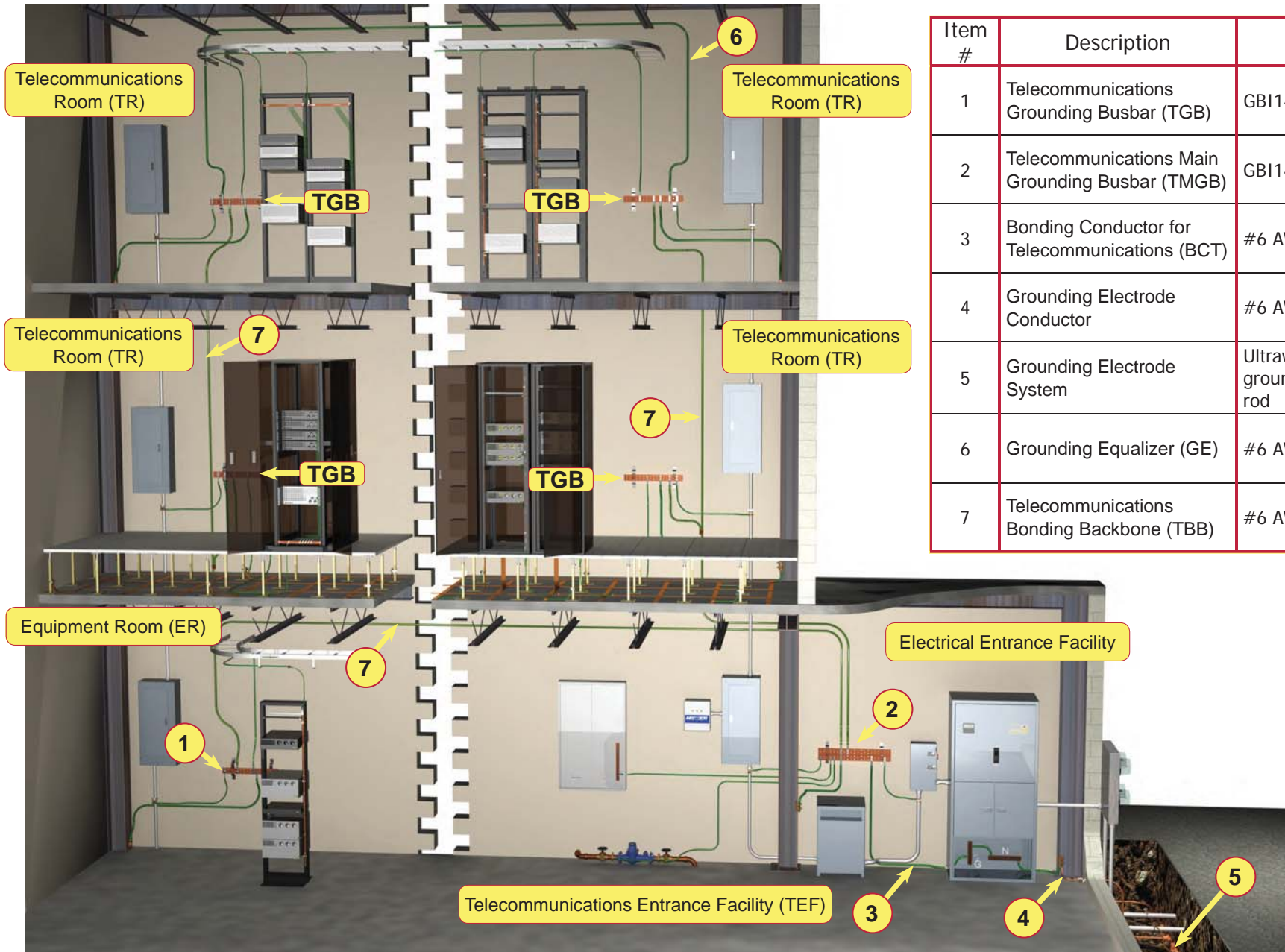


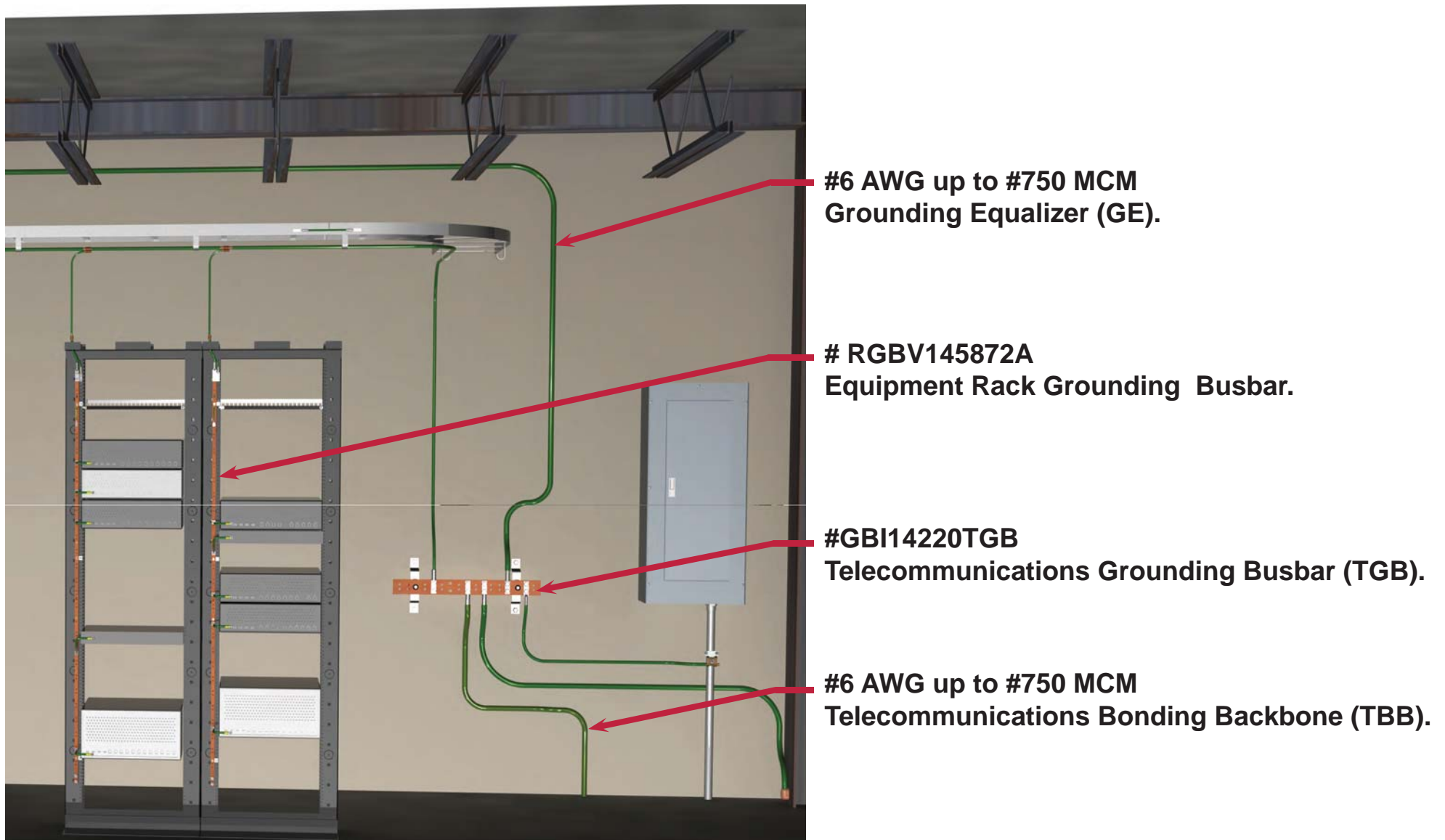
Overview of Telecommunications Bonding & Grounding Systems



Item #	Description	Part Number
1	Telecommunications Grounding Busbar (TGB)	GBI14220TGB
2	Telecommunications Main Grounding Busbar (TMGB)	GBI14420TGB
3	Bonding Conductor for Telecommunications (BCT)	#6 AWG up to #750 MCM
4	Grounding Electrode Conductor	#6 AWG up to #750 MCM
5	Grounding Electrode System	Ultraweld connection to ground conductor & ground rod
6	Grounding Equalizer (GE)	#6 AWG up to #750 MCM
7	Telecommunications Bonding Backbone (TBB)	#6 AWG up to #750 MCM

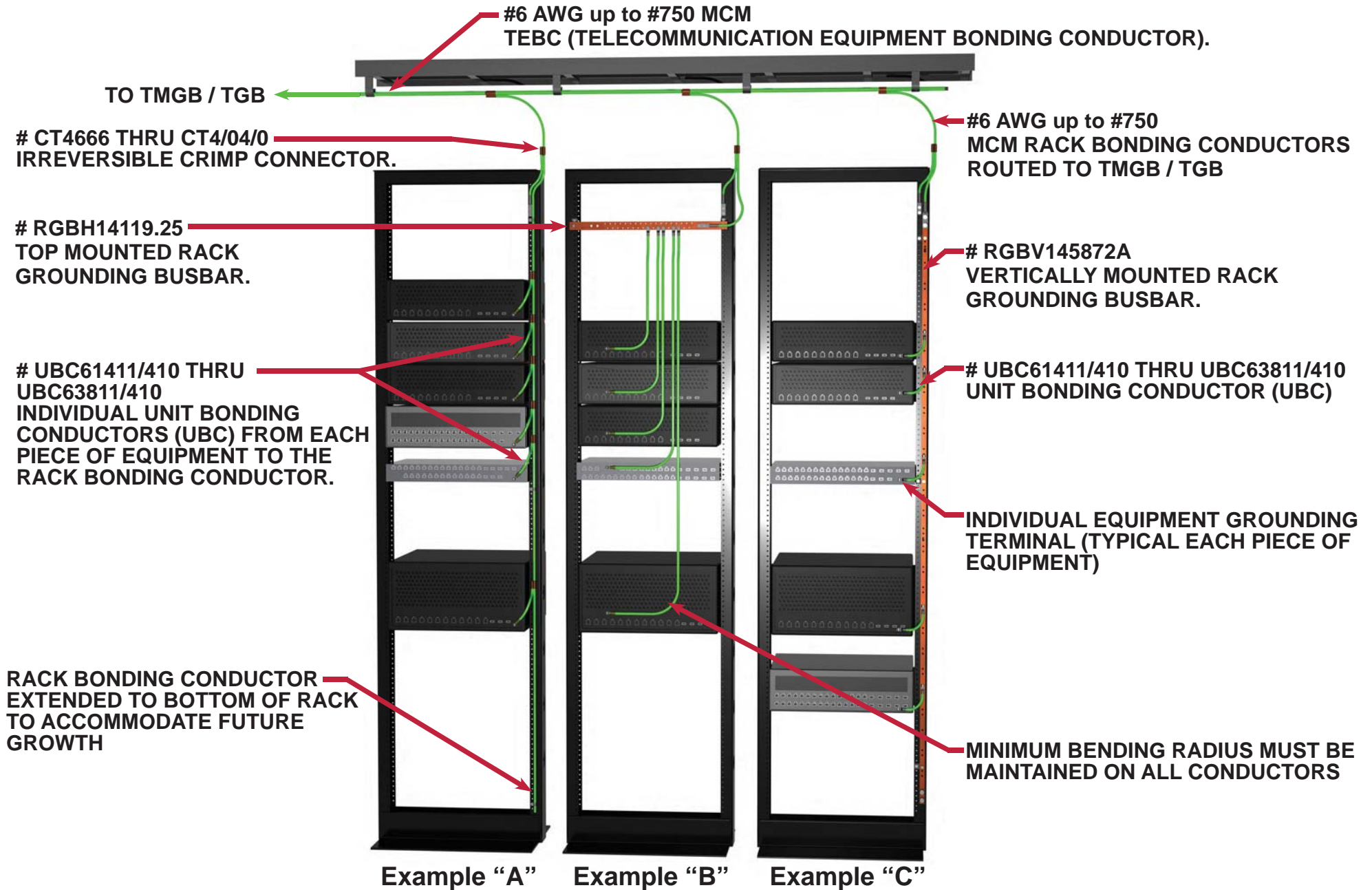
Sizing the Grounding Equalizer (GE)

- The GE shall be, as a minimum, the same size as the largest TBB.



Courtesy of **HARGER**

Equipment Rack Bonding



Example of three methods to bond equipment racks to ground.

Courtesy of **HARGER**

Grounding Equalizer (GE)

- When two or more TBB's are used in a multistory building, the TBB's shall be bonded together with a GE at the top floor and at a minimum of every third floor in between to the lowest floor level.

